imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

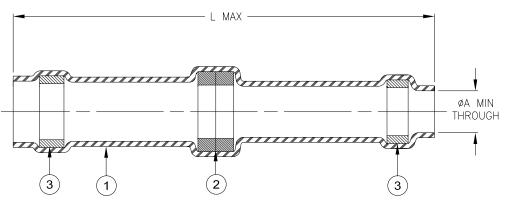


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CUSTOMER DRAWING



	Size Code Color	Product Dimensions		Selection Guide						
Part Name				Wire Gauge AWG	Section mm ²	Total CMA	Total mm ²	Wire Dimensions		
		ØA min	L max	min max	min max	min max	min max	ØB min	ØB max C max	C min
B-155-008-11	Clear	1.7	26.0	2x26	2x0.15	600	0.3	0.76	1.5	1.0
		(0.065)	(1.025)	2x24	2x0.3	1000	0.6	(0.03)	(0.06)	(0.039)
B-155-008-13	Red	2.3	31.0	2x22	2x0.4	1500	0.8	1.5	2.0	1.8
		(0.090)	(1.220)	2x18	2x1	3800	2.0	(0.060)	(0.090)	(0.070)
B-155-008-14	Blue	4.3	36.0	2x18	2x1	3800	2.0	2.0	4.0	2.3
		(0.170)	(1.420)	2x12	2x3	12000	6.0	(0.080)	(0.170)	(0.090)
B-155-008-15	Yellow	6.8	42.0	2x12	2x3	12000	6.0	3.4	6.5	3.7
		(0.268)	(1.660)	2x10	2x5	25000	10.0	(0.135)	(0.270)	(0.145)

MATERIALS

1. INSULATION SLEEVE: Heat-shrinkable, transparent gray, radiation cross-linked modified polyolefin.

2. SOLDER PREFORM WITH FLUX: (Qty.: 2 except for B-155-008-11 Qty. 1)

SOLDER: TYPE Sn42Bi58 per ANSI / J-STD-006.

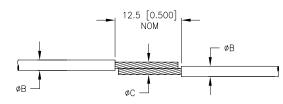
FLUX: TYPE ROM1 per ANSI / J-STD-004.

3. MELTABLE RINGS: Thermally stabilized thermoplastic. Color: see table.

APPLICATION

1. These controlled soldering devices are designed to splice tin-plated or bare copper wires rated for at least +85°C.

- 2. Temperature range: -55°C to +125°C.
- 3. For installation procedure and application equipment, consult RPIP-850-00.
- 4. For best results, prepare the wire as shown below.



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Ē⊤yo	o Electi	onics	Tyc o Ele c tronic s 305 C onstitution Dr Menlo Park, CA 94025, U.S.A.	TITLE: SOLDERSLEEVE WIRE TO WIRE SPLICE, ROHS COMPLIANT, LOW TEMPERATURE				
Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets]			Raychem Devices	DOCUMENT NO.: B-155-008-1X				
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	ANGLES: N/A ROUGHNESS IN MICRON	Tyco Electronics reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application.		REV: C	DATE: Dece	DATE: December 2, 2008		
REVISED BY: YUNGUYEN	CAGE CODE: 06090	REPLACES: 08-015992	ECO NUMBER: 08-029674	SCALE: NTS	SIZE: A	SHEET: 1 of 1		

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